



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-11-22
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacopello	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC6H065DI	HSUR*3D101T6	A	SH1A	2017-11-22
	Amount	UoM	Unit type	ST ECOPACK Grade
	2170.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10,15.5,4.5	2	Through-hole	
Comment				

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 21st October 2016			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	Die	11
Lead	4.56	Soft solder	2100

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HSUR*3D101T6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.814	mg	supplier	die	Silicium carbide	409-21-2		2.734	mg	971571	1260
				supplier	metallization	Aluminium (Al)	7429-90-5		0.016	mg	5686	7
				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	711	1
				supplier	passivation	Nickel (Ni)	7440-02-0		0.013	mg	4620	6
				supplier	metallization	Silver (Ag)	7440-22-4		0.027	mg	9595	12
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	355	0
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	355	0
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	710	1
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.011	mg	3909	5
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.007	mg	2488	3
Leadframe	Copper & its alloys	1559.632	mg	supplier	alloy	Copper (Cu)	7440-50-8		1557.605	mg	998700	717790
				supplier	alloy	Iron (Fe)	7439-89-6		0.717	mg	460	330
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		1.310	mg	840	604
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	4.558	mg	850056	2100
Soft solder	Solder	5.362	mg	JIG - R	solder	Antimony (Sb)	7440-36-0		0.536	mg	99963	247
				supplier	solder	Tin (Sn)	7440-31-5		0.268	mg	49981	124
				supplier	wire	Aluminium (Al)	7429-90-5		1.231	mg	1000000	567
Encapsulation	Other Organic Materials	596.752	mg	supplier	mold compound	Silica, vitreous	60676-86-0		453.531	mg	759999	209000
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		60.869	mg	102000	28050
				supplier	mold compound	Phenol resin	9003-35-4		35.805	mg	60000	16500
				supplier	mold compound	Others	Proprietary		29.838	mg	50001	13750
				supplier	mold compound	Metal hydroxide	Proprietary		11.935	mg	20000	5500
connections coating	Solder	4.209	mg	supplier	mold compound	Carbon black	1333-86-4		4.774	mg	8000	2200
				supplier	solder alloy	Tin (Sn)	7440-31-5		4.209	mg	1000000	1940